



(12) **United States Patent**
McCalley et al.

(10) **Patent No.:** **US 9,638,944 B1**
(45) **Date of Patent:** **May 2, 2017**

(54) **SYSTEMS AND METHODS FOR SUBSTRATE LAMINATION**

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 227 days.

(21) Appl. No.: **14/270,563**

(22) Filed: **May 6, 2014**

(51) **Int. Cl.**
G02F 1/1333 (2006.01)

(52) **U.S. Cl.**
CPC **G02F 1/1333** (2013.01)

(58) **Field of Classification Search**
CPC G02F 1/1333
USPC 156/285, 286
See application file for complete search history.

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(57) **ABSTRACT**

A method for laminating substrates to form a laminated assembly includes positioning a first substrate and a second substrate within a lamination device having a first cavity and a second cavity; pressurizing the first cavity to a first pressure to move a flexible member into contact with one of the first and second substrate; depressurizing the first cavity to move the flexible member out of contact with the one of the first and second substrate; and pressurizing a second cavity to a second pressure higher than the first pressure to apply air pressure at the second pressure to the first and second substrate to form a laminated assembly.

20 Claims, 5 Drawing Sheets

